

Title (en)
DEVICE AND METHOD FOR ELECTROPLATING

Title (de)
VORRICHTUNG UND VERFAHREN ZUR GALVANISCHEN BESCHICHTUNG

Title (fr)
DISPOSITIF ET PROCÉDÉ DE REVÊTEMENT PAR ÉLECTROLYSE

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Application
EP 07847339 A 20071126

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Abstract (en)
[origin: WO2008065069A1] The invention relates to a device for the electroplating of a surface of a substrate (7) with a structured or fully flat base layer (9), which device comprises at least one electrolytic bath (3) with at least one rotatably mounted roller (2) which can be connected as a cathode and, during the electroplating, contacts the base layer (9), wherein the base layer (9) is covered by an electrolyte solution (5) contained in the electrolytic bath (3) and is moved in relation to the at least one roller (2) during the coating. The at least one roller (2) which can be connected as a cathode is cathodically connected during the contact with the base layer (9) and becomes currentless or anodically connected as soon as there is no contact with the base layer (9). The invention also relates to a method for the electroplating of a surface of a substrate (7) with a structured or fully flat base layer (9), wherein the base layer (9) is surrounded by an electrolyte solution (5) and is contacted by at least one roller (2) which can be connected as a cathode. The roller (2) which can be connected as a cathode is cathodically connected when it contacts the base layer (9) and becomes currentless or is anodically connected as soon as there is no contact with the base layer (9).

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